(Albany, NY) July 16, 2018: YINCAE is excited to announce that we will be attending the 15th Annual International Wafer-Level Packaging Conference and Tabletop Exhibition in San Jose, CA this year from October 23rd-25th at the Double Tree by Hilton. This conference brings together many of the top performers in the semiconductor industry and addresses all aspects of wafer-level, 3D, TSV, and MEMS device packaging and manufacturing.

As we prepare for the upcoming event, we hope that you are looking to attend the show as well. Come by our Booth 47 and take one of our informative pamphlets, learn more about the array of products we supply, and ask us any questions that you may have. YINCAE hopes that you will be attending the show and stop by to learn more about our company and the innovative products that we have to offer!

YINCAE has unique and exclusive products that no other company has developed. There is a lot that can be taken away from not only our booth and products, but from the IWLPC 2018 as a whole. YINCAE hopes to see you there at the IWLPC 2018 at Booth 47!

* * * * * * * *

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

###

The YINCAE brand name and logo are trademarks of YINCAE Advanced Materials, LLC.